

## Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

## Features

- ◆ 45V, 5A,  $R_{DS(ON).max}=30m\Omega @ V_{GS}=10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ Green device available

## Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

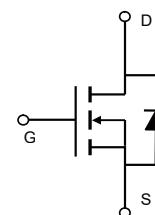
## Product Summary

$V_{DSS}$	45V
$R_{DS(on).max} @ V_{GS}=10V$	30mΩ
$I_D$	5A

## SOP-8 Pin Configuration



SOP-8



Schematic

## Absolute Maximum Ratings

 $T_A = 25^\circ C$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	45	V
Continuous drain current ( $T_A = 25^\circ C$ )	$I_D$	5	A
Continuous drain current ( $T_A = 100^\circ C$ )		3.2	A
Pulsed drain current <sup>1)</sup>	$I_{DM}$	20	A
Gate-Source voltage	$V_{GSS}$	$\pm 20$	V
Power Dissipation ( $T_A = 25^\circ C$ )	$P_D$	1.3	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	96	°C/W

## Package Marking and Ordering Information

Device	Device Package	Marking
VSM5N04-S8	SOP-8	VSM5N04-S8

## Electrical Characteristics

T<sub>J</sub> = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250μA	45	---	---	V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	---	2.0	V
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =45V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 25°C	---	---	1	μA
		V <sub>DS</sub> =36V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 125°C	---	---	10	μA
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =20 V, V <sub>DS</sub> =0V	---	---	100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-20 V, V <sub>DS</sub> =0V	---	---	-100	nA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10 V, I <sub>D</sub> =5A	---	25	30	mΩ
		V <sub>GS</sub> =4.5 V, I <sub>D</sub> =4A	---	30	45	mΩ
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5 V , I <sub>D</sub> =5A	---	9.9	---	S
<b>Dynamic characteristics</b>						
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0 V, F = 1MHz	---	597	---	pF
Output capacitance	C <sub>oss</sub>		---	56	---	
Reverse transfer capacitance	C <sub>rss</sub>		---	43	---	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = 25V, V <sub>GS</sub> =10V, I <sub>D</sub> =5A	---	13.5	---	ns
Rise time	t <sub>r</sub>		---	12	---	
Turn-off delay time	t <sub>d(off)</sub>		---	43	---	
Fall time	t <sub>f</sub>		---	11	---	
<b>Gate charge characteristics</b>						
Gate to source charge	Q <sub>gs</sub>	V <sub>DS</sub> =25V, I <sub>D</sub> =5A, V <sub>GS</sub> = 10 V	---	3.3	---	nC
Gate to drain charge	Q <sub>gd</sub>		---	1.6	---	
Gate charge total	Q <sub>g</sub>		---	12.3	---	
<b>Drain-Source diode characteristics and Maximum Ratings</b>						
Continuous Source Current	I <sub>s</sub>		---	---	5	A
Pulsed Source Current	I <sub>SM</sub>		---	---	20	A
Diode Forward Voltage <sup>2)</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>s</sub> =5A, T <sub>J</sub> =25°C	---	---	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>s</sub> =5A,di/dt=100A/us, T <sub>J</sub> =25°C	---	18.5	---	ns
Reverse Recovery Charge	Q <sub>rr</sub>		---	6.5	---	nC

Notes:

1: Repetitive Rating: Pulse width limited by maximum junction temperature.

2: Pulse Test: Pulse Width ≤300 μ s, Duty Cycle≤2%.

## Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

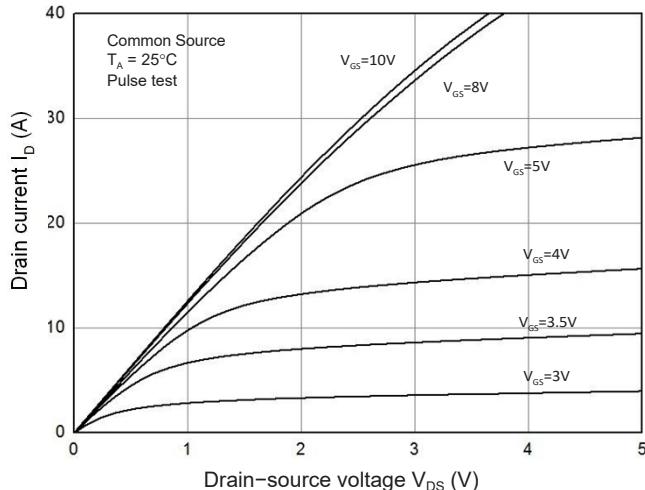


Figure 2. Transfer Characteristics

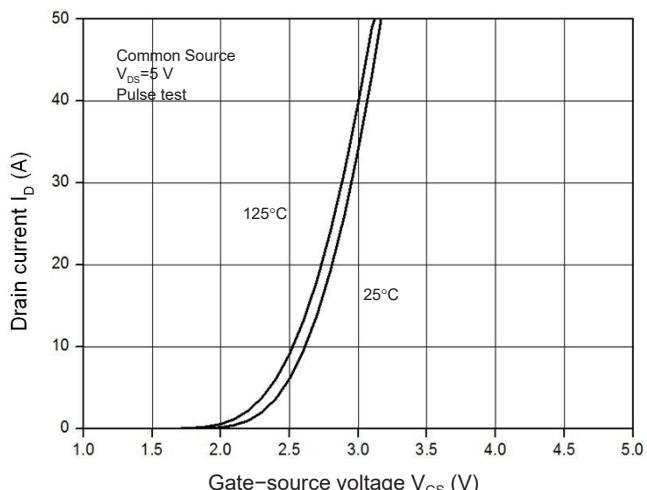


Figure 3. Capacitance Characteristics

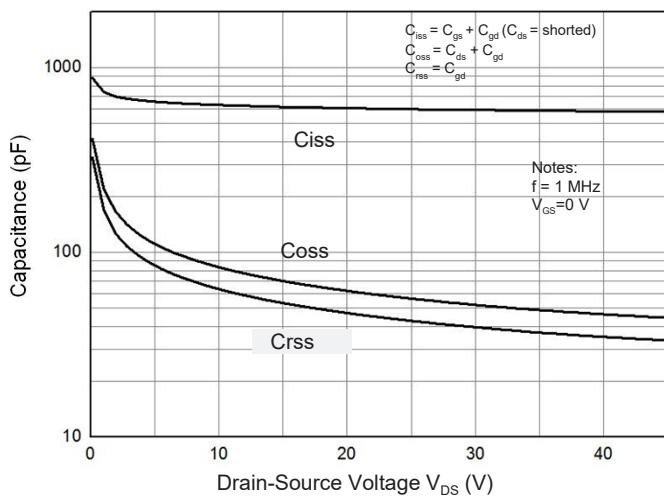


Figure 4. Gate Charge Waveform

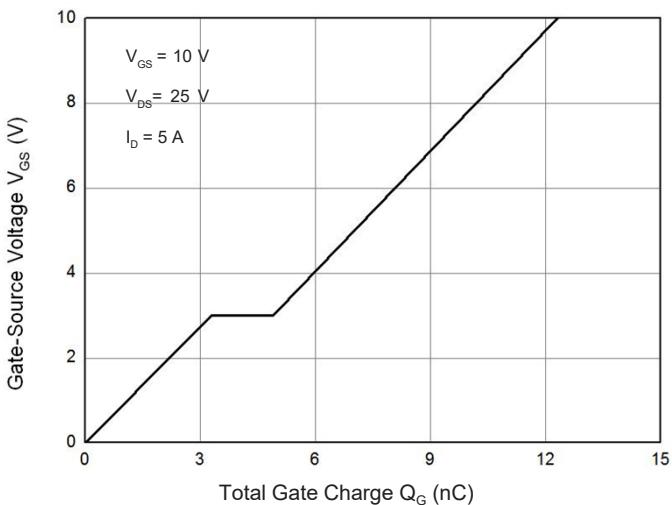


Figure 5. Body-Diode Characteristics

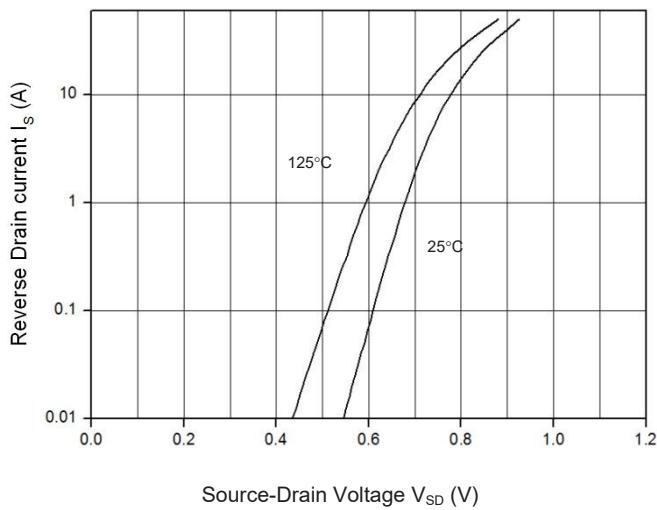


Figure 6. Rdson-Drain Current

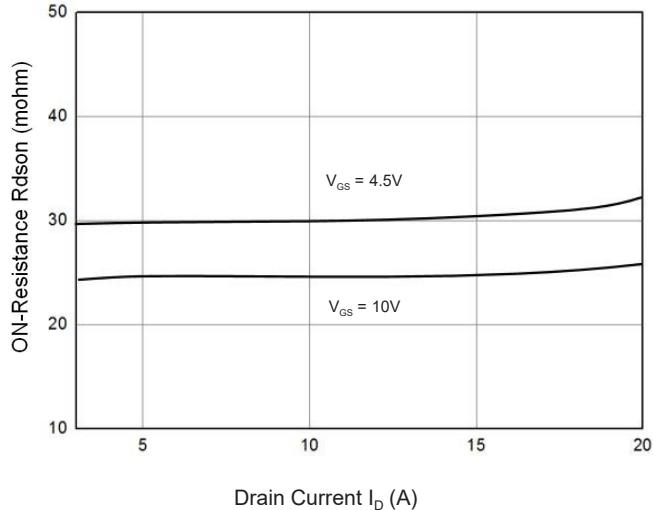


Figure 7. Rdson-Junction Temperature(°C)

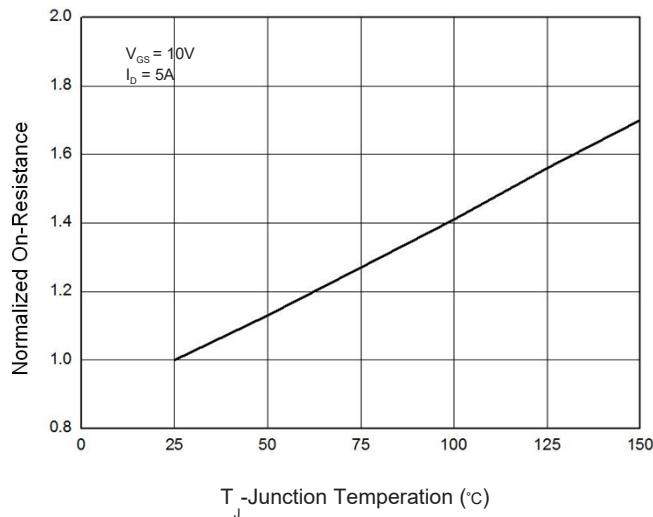


Figure 8. Maximum Safe Operating Area

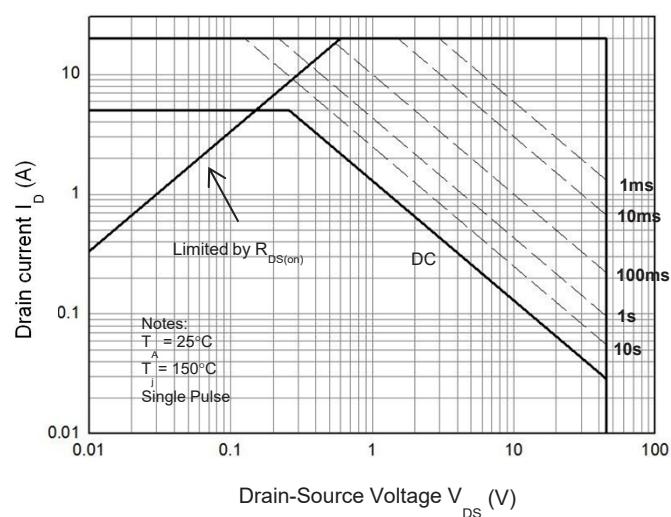
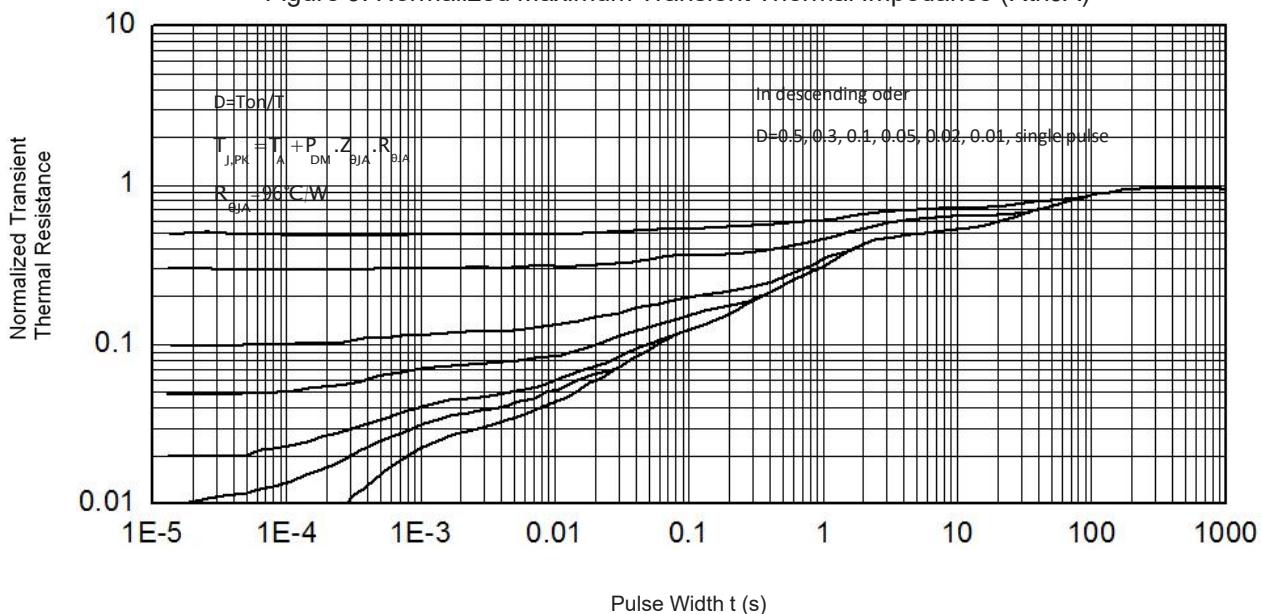


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJA)



## Test Circuit & Waveform

Figure 8. Gate Charge Test Circuit & Waveform

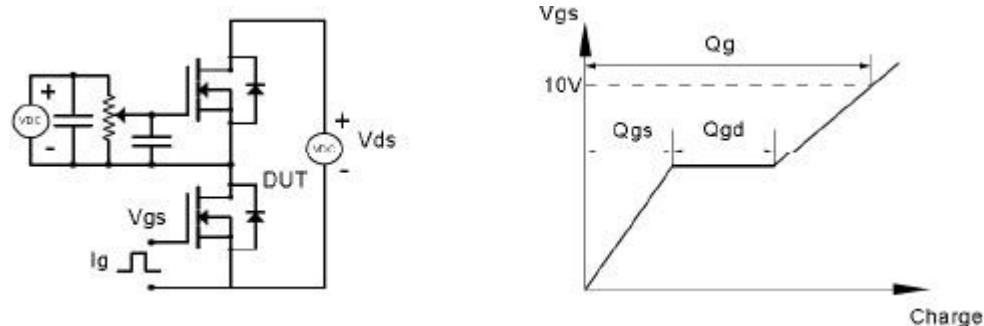


Figure 9. Resistive Switching Test Circuit & Waveforms

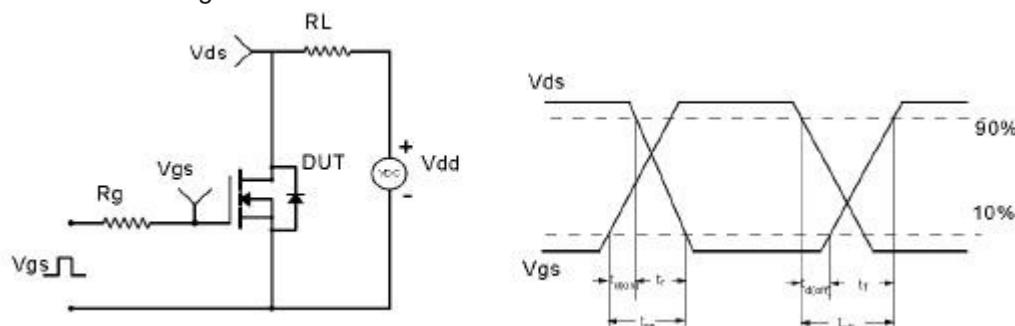


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

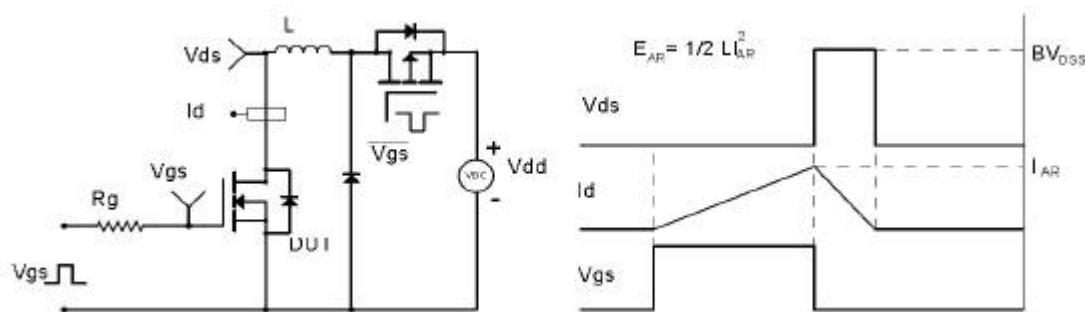


Figure 11. Diode Recovery Circuit & Waveform

